

ABSTRACT OF THE DISCLOSURE

Silver paste is applied to a stem, and a semiconductor laser chip is mounted onto the stem on which the silver paste has been applied. Next, the semiconductor laser chip mounted on the stem, while kept pressurized toward the stem with a collet, is heated to make the silver paste temporarily cured, by which the semiconductor laser chip is fixed onto the stem. Then, after a temporary curing step, the silver paste is finally cured within a thermostat. The semiconductor laser device thus manufactured is low in thermal resistance and reduced in variations of operating current and prevented from short-circuiting of the semiconductor laser chip.

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